

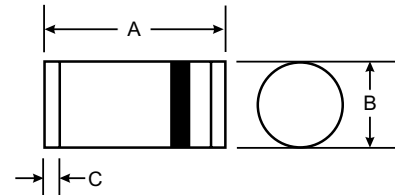
VOLTAGE RANGE: 50 - 1000V
CURRENT: 1.0 A

Features

- Plastic package has underwriters laboratories
- flammability classification 94V-0
- Glass passivated chip junction
- For surface mount applications
- High temperature metallurgically bonded construction
- Cavity-free glass passivated junction
- High temperature soldering guaranteed: 450 /5 seconds
- at terminals. Complete device sub-mersible temperature
- of 265

Mechanical Data

- Case: JEDEC DO-213AB(LL41), molded plastic
- Polarity: Color band denotes cathode
- Weight: 0.0046 ounces, 0.116 grams
- Mounting position: Any



LL41/ DO-213AB		
Dim	Min	Max
A	4.80	5.20
B	2.40	2.60
C	0.55 Nominal	
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics T_A = 25°C unless otherwise specified

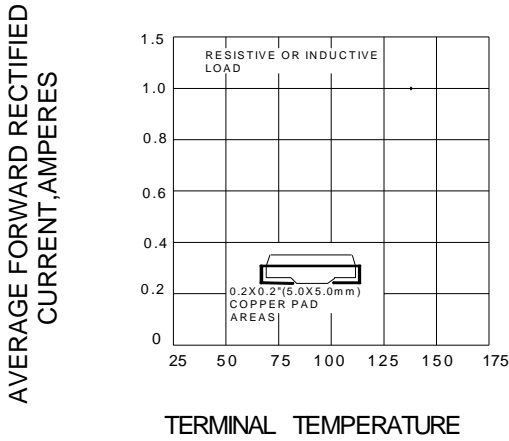
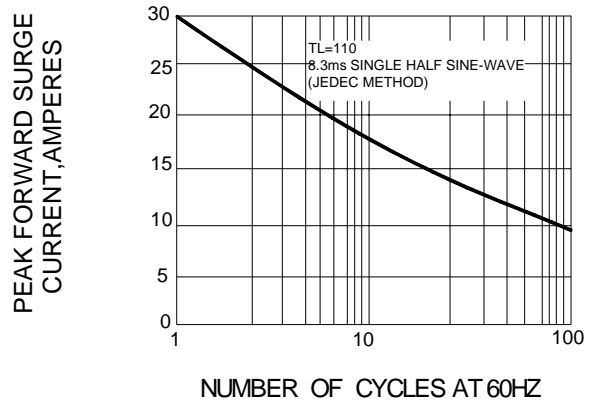
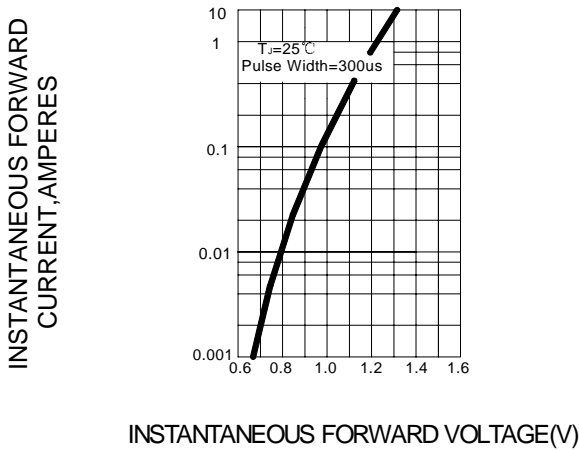
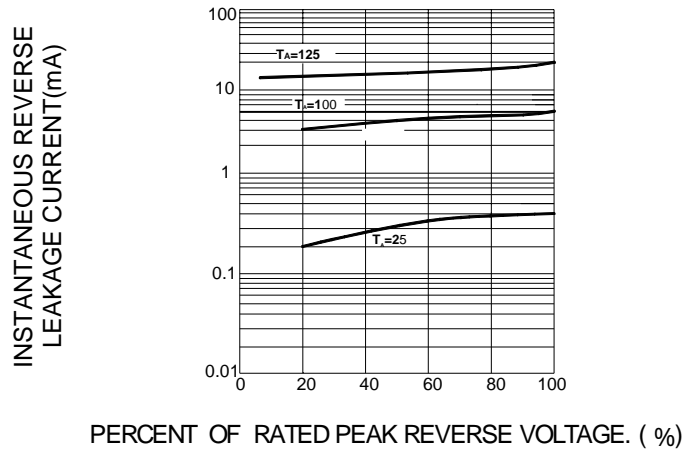
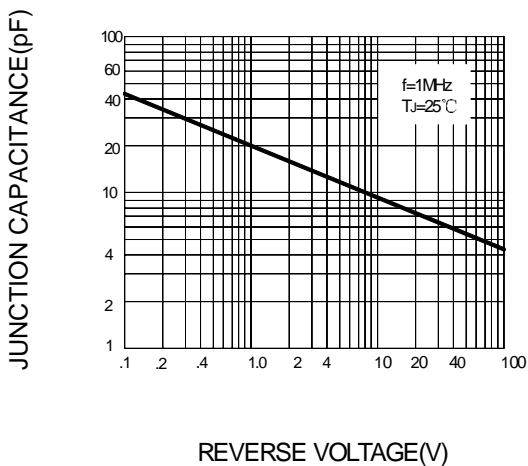
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	RGL	RGL	RGL	RGL	RGL	RGL	RGL	UNITS
		41A	41B	41D	41G	41J	41K	41M	
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current T _T =55	I _(AV)	1.0							A
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30							A
Maximum instantaneous forward voltage @1.0A	V _F	1.3							V
Maximum reverse current @T _A =25 at rated DC blocking voltage @T _A =125	I _R	5.0 50							μA
Maximum reverse recovery time (Note 1)	t _{rr}	150				250	500		ns
Typical junction capacitance (Note 2)	C _j	15							pF
Typical thermal resistance (Note 3)	R _{θJA}								/W
Operating junction temperature range	T _j	- 55 ---- +175							
Storage temperature range	T _{STG}	- 55 ---- +175							

NOTE: 1. Measured with I_F=0.5A, I_R=1.0A, I_{rr}=0.25A

2. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

3. Thermal resistance from junction to ambient, 0.24x0.24"(6.0x6.0mm) copper pads to each terminal.

FIG.1 – FORWARD CURRENT DERATING CURVE

FIG.2 – MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

FIG.3 – TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

FIG.4 – TYPICAL REVERSE CHARACTERISTICS

FIG.5 – TYPICAL JUNCTION CAPACITANCE

FIG.6 – TYPICAL TRANSIENT THERMAL IMPEDANCE
